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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	294912
Number of I/O	173
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400-4ft256c

PRODUCT NOT RECOMMENDED FOR NEW DESIGNS

Spartan-3 FPGA Family: Introduction and Ordering Information

DS099 (v3.0) October 29, 2012 **Product Specification**

Introduction

The Spartan®-3 family of Field-Programmable Gate Arrays is specifically designed to meet the needs of high volume, cost-sensitive consumer electronic applications. The eight-member family offers densities ranging from 50,000 to 5,000,000 system gates, as shown in Table 1.

The Spartan-3 family builds on the success of the earlier Spartan-IIE family by increasing the amount of logic resources, the capacity of internal RAM, the total number of I/Os, and the overall level of performance as well as by improving clock management functions. Numerous enhancements derive from the Virtex®-II platform technology. These Spartan-3 FPGA enhancements, combined with advanced process technology, deliver more functionality and bandwidth per dollar than was previously possible, setting new standards in the programmable logic industry.

Because of their exceptionally low cost, Spartan-3 FPGAs are ideally suited to a wide range of consumer electronics applications, including broadband access, home networking, display/projection and digital television equipment.

The Spartan-3 family is a superior alternative to mask programmed ASICs. FPGAs avoid the high initial cost, the lengthy development cycles, and the inherent inflexibility of conventional ASICs. Also, FPGA programmability permits design upgrades in the field with no hardware replacement necessary, an impossibility with ASICs.

Features

- Low-cost, high-performance logic solution for high-volume, consumer-oriented applications
  - Densities up to 74,880 logic cells
- SelectIO™ interface signaling
  - Up to 633 I/O pins
  - 622+ Mb/s data transfer rate per I/O
  - 18 single-ended signal standards
  - 8 differential I/O standards including LVDS, RSDS
  - Termination by Digitally Controlled Impedance
  - Signal swing ranging from 1.14V to 3.465V
  - Double Data Rate (DDR) support
  - DDR, DDR2 SDRAM support up to 333 Mb/s
- Logic resources
  - Abundant logic cells with shift register capability
  - Wide, fast multiplexers
  - Fast look-ahead carry logic
  - Dedicated 18 x 18 multipliers
  - JTAG logic compatible with IEEE 1149.1/1532
- SelectRAM™ hierarchical memory
  - Up to 1,872 Kbits of total block RAM
  - Up to 520 Kbits of total distributed RAM
- Digital Clock Manager (up to four DCMs)
  - Clock skew elimination
  - Frequency synthesis
  - High resolution phase shifting
- Eight global clock lines and abundant routing
- Fully supported by Xilinx ISE® and WebPACK™ software development systems
- MicroBlaze™ and PicoBlaze™ processor, PCI®, PCI Express® PIPE Endpoint, and other IP cores
- Pb-free packaging options
- Automotive Spartan-3 XA Family variant

Table 1: **Summary of Spartan-3 FPGA Attributes**

Device	System Gates	Equivalent Logic Cells[1]	CLB Array (One CLB = Four Slices)			Distributed RAM Bits (K=1024)	Block RAM Bits (K=1024)	Dedicated Multipliers	DCMs	Max. User I/O	Maximum Differential I/O Pairs
			Rows	Columns	Total CLBs						
XC3S50[2]	50K	1,728	16	12	192	12K	72K	4	2	124	56
XC3S200[2]	200K	4,320	24	20	480	30K	216K	12	4	173	76
XC3S400[2]	400K	8,064	32	28	896	56K	288K	16	4	264	116
XC3S1000[2]	1M	17,280	48	40	1,920	120K	432K	24	4	391	175
XC3S1500	1.5M	29,952	64	52	3,328	208K	576K	32	4	487	221
XC3S2000	2M	46,080	80	64	5,120	320K	720K	40	4	565	270
XC3S4000	4M	62,208	96	72	6,912	432K	1,728K	96	4	633	300
XC3S5000	5M	74,880	104	80	8,320	520K	1,872K	104	4	633	300

Notes:
1. Logic Cell = 4-input Look-Up Table (LUT) plus a 'D' flip-flop. "Equivalent Logic Cells" equals "Total CLBs" x 8 Logic Cells/CLB x 1.125 effectiveness.
2. These devices are available in Xilinx Automotive versions as described in DS314: *Spartan-3 Automotive XA FPGA Family.*

IOBs

For additional information, refer to the chapter entitled "Using I/O Resources" in UG331: *Spartan-3 Generation FPGA User Guide*.

IOB Overview

The Input/Output Block (IOB) provides a programmable, bidirectional interface between an I/O pin and the FPGA's internal logic.

A simplified diagram of the IOB's internal structure appears in Figure 7. There are three main signal paths within the IOB: the output path, input path, and 3-state path. Each path has its own pair of storage elements that can act as either registers or latches. For more information, see the Storage Element Functions section. The three main signal paths are as follows:

- The input path carries data from the pad, which is bonded to a package pin, through an optional programmable delay element directly to the I line. There are alternate routes through a pair of storage elements to the IQ1 and IQ2 lines. The IOB outputs I, IQ1, and IQ2 all lead to the FPGA's internal logic. The delay element can be set to ensure a hold time of zero.
- The output path, starting with the O1 and O2 lines, carries data from the FPGA's internal logic through a multiplexer and then a three-state driver to the IOB pad. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements.
- The 3-state path determines when the output driver is high impedance. The T1 and T2 lines carry data from the FPGA's internal logic through a multiplexer to the output driver. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements. When the T1 or T2 lines are asserted High, the output driver is high-impedance (floating, hi-Z). The output driver is active-Low enabled.
- All signal paths entering the IOB, including those associated with the storage elements, have an inverter option. Any inverter placed on these paths is automatically absorbed into the IOB.

Storage Element Functions

There are three pairs of storage elements in each IOB, one pair for each of the three paths. It is possible to configure each of these storage elements as an edge-triggered D-type flip-flop (FD) or a level-sensitive latch (LD).

The storage-element-pair on either the Output path or the Three-State path can be used together with a special multiplexer to produce Double-Data-Rate (DDR) transmission. This is accomplished by taking data synchronized to the clock signal's rising edge and converting them to bits synchronized on both the rising and the falling edge. The combination of two registers and a multiplexer is referred to as a Double-Data-Rate D-type flip-flop (FDDR). See Double-Data-Rate Transmission, page 12 for more information.

The signal paths associated with the storage element are described in Table 5.

Table 5: **Storage Element Signal Description**

Storage Element Signal	Description	Function
D	Data input	Data at this input is stored on the active edge of CK enabled by CE. For latch operation when the input is enabled, data passes directly to the output Q.
Q	Data output	The data on this output reflects the state of the storage element. For operation as a latch in transparent mode, Q will mirror the data at D.
CK	Clock input	A signal's active edge on this input with CE asserted, loads data into the storage element.
CE	Clock Enable input	When asserted, this input enables CK. If not connected, CE defaults to the asserted state.
SR	Set/Reset	Forces storage element into the state specified by the SRHIGH/SRLOW attributes. The SYNC/ASYNC attribute setting determines if the SR input is synchronized to the clock or not.
REV	Reverse	Used together with SR. Forces storage element into the state opposite from what SR does.

The DCI feature operates independently for each of the device's eight banks. Each bank has an 'N' reference pin (VRN) and a 'P' reference pin, (VRP), to calibrate driver and termination resistance. Only when using a DCI standard on a given bank do these two pins function as VRN and VRP. When not using a DCI standard, the two pins function as user I/Os. As shown in Figure 9, add an external reference resistor to pull the VRN pin up to V_{CCO} and another reference resistor to pull the VRP pin down to GND. Also see Figure 42, page 116. Both resistors have the same value—commonly 50Ω—with one-percent tolerance, which is either the characteristic impedance of the line or twice that, depending on the DCI standard in use. Standards having a symbol name that contains the letters "DV2" use a reference resistor value that is twice the line impedance. DCI adjusts the output driver impedance to match the reference resistors' value or half that, according to the standard. DCI always adjusts the on-chip termination resistors to directly match the reference resistors' value.

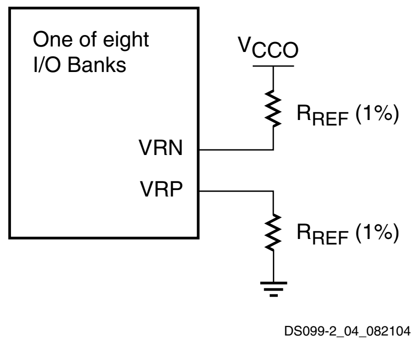


Figure 9: **Connection of Reference Resistors (R_{REF})**

The rules guiding the use of DCI standards on banks are as follows:

- No more than one DCI I/O standard with a Single Termination is allowed per bank.
- No more than one DCI I/O standard with a Split Termination is allowed per bank.
- Single Termination, Split Termination, Controlled- Impedance Driver, and Controlled-Impedance Driver with Half Impedance can co-exist in the same bank.

See also The Organization of IOBs into Banks, immediately below, and DCI: User I/O or Digitally Controlled Impedance Resistor Reference Input, page 115.

The Organization of IOBs into Banks

IOBs are allocated among eight banks, so that each side of the device has two banks, as shown in Figure 10. For all packages, each bank has independent V_{REF} lines. For example, V_{REF} Bank 3 lines are separate from the V_{REF} lines going to all other banks.

For the Very Thin Quad Flat Pack (VQ), Plastic Quad Flat Pack (PQ), Fine Pitch Thin Ball Grid Array (FT), and Fine Pitch Ball Grid Array (FG) packages, each bank has dedicated V_{CCO} lines. For example, the V_{CCO} Bank 7 lines are separate from the V_{CCO} lines going to all other banks. Thus, Spartan-3 devices in these packages support eight independent V_{CCO} supplies.

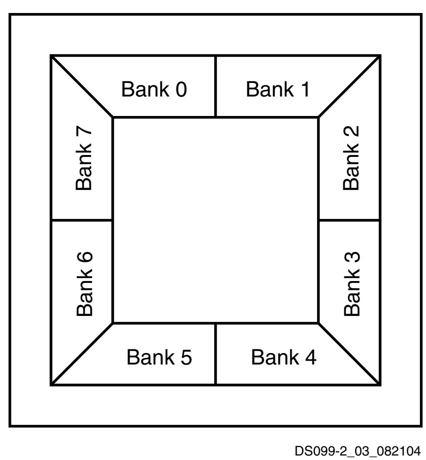


Figure 10: **Spartan-3 FPGA I/O Banks (Top View)**

Supply Voltages for the IOBs

Three different supplies power the IOBs:

- The V_{CCO} supplies, one for each of the FPGA's I/O banks, power the output drivers, except when using the GTL and GTLP signal standards. The voltage on the V_{CCO} pins determines the voltage swing of the output signal.
- V_{CCINT} is the main power supply for the FPGA's internal logic.
- The V_{CCAUX} is an auxiliary source of power, primarily to optimize the performance of various FPGA functions such as I/O switching.

The I/Os During Power-On, Configuration, and User Mode

With no power applied to the FPGA, all I/Os are in a high-impedance state. The V_{CCINT} (1.2V), V_{CCAUX} (2.5V), and V_{CCO} supplies may be applied in any order. Before power-on can finish, V_{CCINT}, V_{CCO} Bank 4, and V_{CCAUX} must have reached their respective minimum recommended operating levels (see Table 29, page 59). At this time, all I/O drivers also will be in a high-impedance state. V_{CCO} Bank 4, V_{CCINT}, and V_{CCAUX} serve as inputs to the internal Power-On Reset circuit (POR).

A Low level applied to the HSWAP_EN input enables pull-up resistors on User I/Os from power-on throughout configuration. A High level on HSWAP_EN disables the pull-up resistors, allowing the I/Os to float. If the HSWAP_EN pin is floating, then an internal pull-up resistor pulls HSWAP_EN High. As soon as power is applied, the FPGA begins initializing its configuration memory. At the same time, the FPGA internally asserts the Global Set-Reset (GSR), which asynchronously resets all IOB storage elements to a Low state.

Upon the completion of initialization, INIT_B goes High, sampling the M0, M1, and M2 inputs to determine the configuration mode. At this point, the configuration data is loaded into the FPGA. The I/O drivers remain in a high-impedance state (with or without pull-up resistors, as determined by the HSWAP_EN input) throughout configuration.

The Global Three State (GTS) net is released during Start-Up, marking the end of configuration and the beginning of design operation in the User mode. At this point, those I/Os to which signals have been assigned go active while all unused I/Os remain in a high-impedance state. The release of the GSR net, also part of Start-up, leaves the IOB registers in a Low state by default, unless the loaded design reverses the polarity of their respective RS inputs.

In User mode, all internal pull-up resistors on the I/Os are disabled and HSWAP_EN becomes a “don't care” input. If it is desirable to have pull-up or pull-down resistors on I/Os carrying signals, the appropriate symbol—e.g., PULLUP, PULLDOWN—must be placed at the appropriate pads in the design. The Bitstream Generator (Bitgen) option UnusedPin available in the Xilinx development software determines whether unused I/Os collectively have pull-up resistors, pull-down resistors, or no resistors in User mode.

CLB Overview

For more details on the CLBs, refer to the chapter entitled “Using Configurable Logic Blocks” in UG331.

The Configurable Logic Blocks (CLBs) constitute the main logic resource for implementing synchronous as well as combinatorial circuits. Each CLB comprises four interconnected slices, as shown in Figure 11. These slices are grouped in pairs. Each pair is organized as a column with an independent carry chain.

The nomenclature that the FPGA Editor—part of the Xilinx development software—uses to designate slices is as follows: The letter ‘X’ followed by a number identifies columns of slices. The ‘X’ number counts up in sequence from the left side of the die to the right. The letter ‘Y’ followed by a number identifies the position of each slice in a pair as well as indicating the CLB row. The ‘Y’ number counts slices starting from the bottom of the die according to the sequence: 0, 1, 0, 1 (the first CLB row); 2, 3, 2, 3 (the second CLB row); etc. Figure 11 shows the CLB located in the lower left-hand corner of the die. Slices X0Y0 and X0Y1 make up the column-pair on the left where as slices X1Y0 and X1Y1 make up the column-pair on the right. For each CLB, the term “left-hand” (or SLICEM) indicates the pair of slices labeled with an even ‘X’ number, such as X0, and the term “right-hand” (or SLICEL) designates the pair of slices with an odd ‘X’ number, e.g., X1.

Interconnect

Interconnect (or routing) passes signals among the various functional elements of Spartan-3 devices. There are four kinds of interconnect: Long lines, Hex lines, Double lines, and Direct lines.

Long lines connect to one out of every six CLBs (see section [a] of Figure 25). Because of their low capacitance, these lines are well-suited for carrying high-frequency signals with minimal loading effects (e.g. skew). If all eight Global Clock Inputs are already committed and there remain additional clock signals to be assigned, Long lines serve as a good alternative.

Hex lines connect one out of every three CLBs (see section [b] of Figure 25). These lines fall between Long lines and Double lines in terms of capability: Hex lines approach the high-frequency characteristics of Long lines at the same time, offering greater connectivity.

Double lines connect to every other CLB (see section [c] of Figure 25). Compared to the types of lines already discussed, Double lines provide a higher degree of flexibility when making connections.

Direct lines afford any CLB direct access to neighboring CLBs (see section [d] of Figure 25). These lines are most often used to conduct a signal from a "source" CLB to a Double, Hex, or Long line and then from the longer interconnect back to a Direct line accessing a "destination" CLB.

For more details, refer to the "*Using Interconnect*" chapter in UG331.

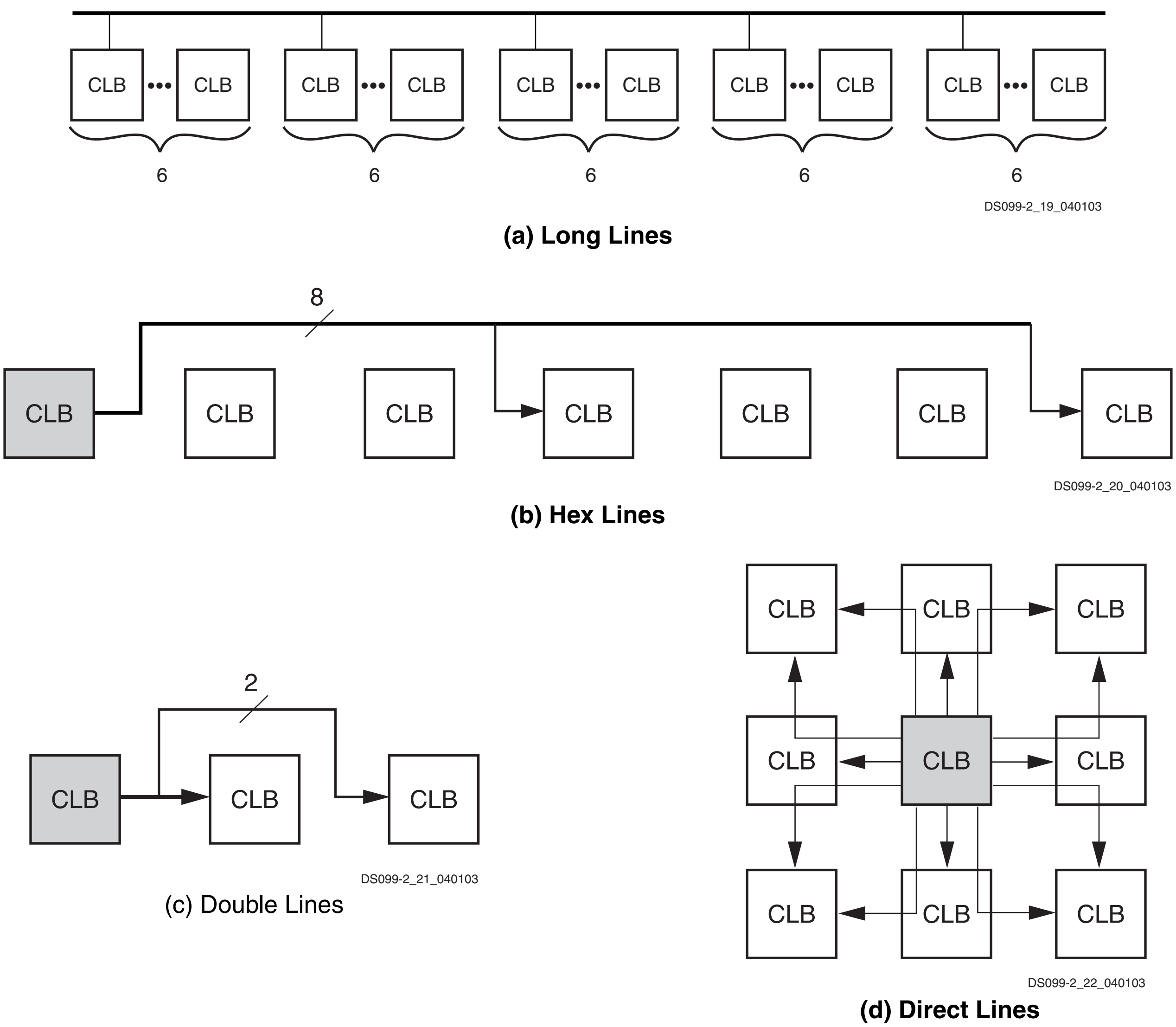
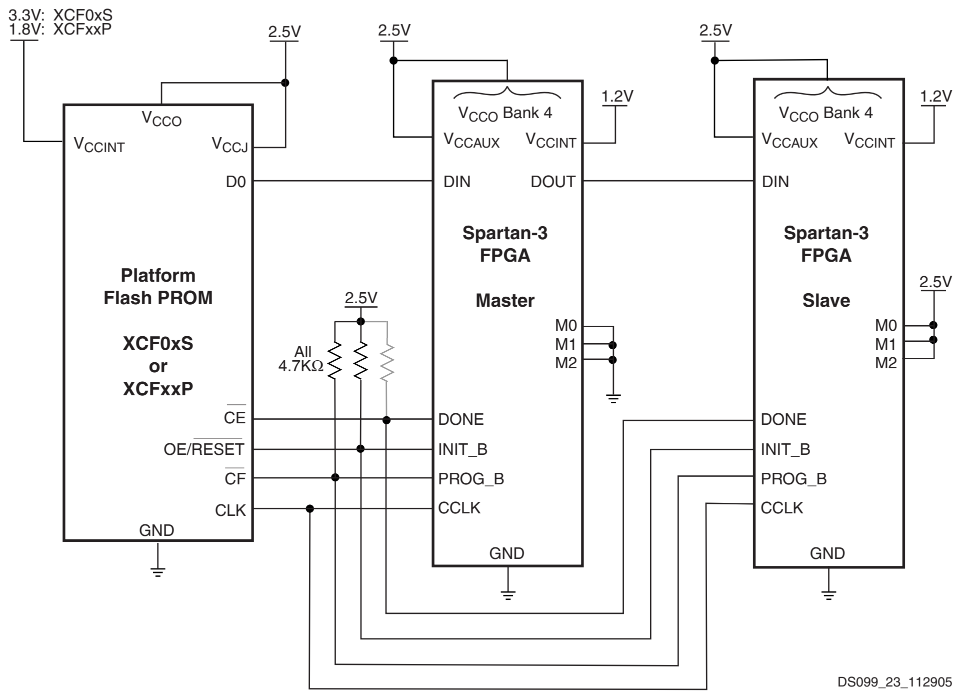


Figure 25: **Types of Interconnect**



Notes:

1. There are two ways to use the DONE line. First, one may set the BitGen option DriveDone to "Yes" only for the last FPGA to be configured in the chain shown above (or for the single FPGA as may be the case). This enables the DONE pin to drive High; thus, no pull-up resistor is necessary. DriveDone is set to "No" for the remaining FPGAs in the chain. Second, DriveDone can be set to "No" for all FPGAs. Then all DONE lines are open-drain and require the pull-up resistor shown in grey. In most cases, a value between 3.3KΩ to 4.7KΩ is sufficient. However, when using DONE synchronously with a long chain of FPGAs, cumulative capacitance may necessitate lower resistor values (e.g. down to 330Ω) in order to ensure a rise time within one clock cycle.
2. For information on how to program the FPGA using 3.3V signals and power, see 3.3V-Tolerant Configuration Interface.

Figure 26: **Connection Diagram for Master and Slave Serial Configuration**

Slave Serial mode is selected by applying <111> to the mode pins (M0, M1, and M2). A pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected.

Master Serial Mode

In Master Serial mode, the FPGA drives CCLK pin, which behaves as a bidirectional I/O pin. The FPGA in the center of Figure 26 is set for Master Serial mode and connects to the serial configuration PROM and to the CCLK inputs of any slave FPGAs in a configuration daisy-chain. The master FPGA drives the configuration clock on the CCLK pin to the Xilinx Serial PROM, which, in response, provides bit-serial data to the FPGA's DIN input. The FPGA accepts this data on each rising CCLK edge. After the master FPGA finishes configuring, it passes data on its DOUT pin to the next FPGA device in a daisy-chain. The DOUT data appears after the falling CCLK clock edge.

The Master Serial mode interface is identical to Slave Serial except that an internal oscillator generates the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a default frequency of 6 MHz. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration.

Slave Parallel Mode (SelectMAP)

The Parallel or SelectMAP modes support the fastest configuration. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data. An external source provides 8-bit-wide data, CCLK, an active-Low Chip Select (CS_B) signal and an active-Low Write signal (RDWR_B). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low. Data can also be read using the Slave Parallel mode. If RDWR_B is asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, it is possible to use any of the Multipurpose pins (DIN/D0-D7, DOUT/BUSY, INIT_B, CS_B, and RDWR_B) as User I/Os. To do this, simply set the BitGen option *Persist* to *No* and assign the desired signals to multipurpose configuration pins using the Xilinx development software. Alternatively, it is possible to continue using the configuration port

Table 30: **Power Voltage Ramp Time Requirements**

Symbol	Description	Device	Package	Min	Max	Units
T_{CCO}	V_{CCO} ramp time for all eight banks	All	All	No limit(4)	–	N/A
T_{CCINT}	V_{CCINT} ramp time, only if V_{CCINT} is last in three-rail power-on sequence	All	All	No limit	No limit(5)	N/A

Notes:

1. If a limit exists, this specification is based on characterization.
2. The ramp time is measured from 10% to 90% of the full nominal voltage swing for all I/O standards.
3. For information on power-on current needs, see Power-On Behavior, page 54
4. For mask revisions earlier than revision E (see Mask and Fab Revisions, page 58), T_{CCO} min is limited to 2.0 ms for the XC3S200 and XC3S400 devices in QFP packages, and limited to 0.6 ms for the XC3S200, XC3S400, XC3S1500, and XC3S4000 devices in the FT and FG packages.
5. For earlier device versions with the FQ fabrication/process code (see Mask and Fab Revisions, page 58), T_{CCINT} max is limited to 500 μs.

Table 31: **Power Voltage Levels Necessary for Preserving RAM Contents**

Symbol	Description	Min	Units
V_{DRINT}	V_{CCINT} level required to retain RAM data	1.0	V
V_{DRAUX}	V_{CCAUX} level required to retain RAM data	2.0	V

Notes:

1. RAM contents include data stored in CMOS configuration latches.
2. The level of the V_{CCO} supply has no effect on data retention.
3. If a brown-out condition occurs where V_{CCAUX} or V_{CCINT} drops below the retention voltage, then V_{CCAUX} or V_{CCINT} must drop below the minimum power-on reset voltage indicated in Table 29 in order to clear out the device configuration content.

Table 32: **General Recommended Operating Conditions**

Symbol	Description		Min	Nom	Max	Units
T_J	Junction temperature	Commercial	0	25	85	°C
		Industrial	–40	25	100	°C
V_{CCINT}	Internal supply voltage		1.140	1.200	1.260	V
V_{CCO}(1)	Output driver supply voltage		1.140	–	3.465	V
V_{CCAUX}	Auxiliary supply voltage		2.375	2.500	2.625	V
ΔV_{CCAUX}(2)	Voltage variance on VCCAUX when using a DCM		–	–	10	mV/ms
V_{IN}(3)	Voltage applied to all User I/O pins and Dual-Purpose pins relative to GND(4)(6)	V_{CCO} = 3.3V, IO	–0.3	–	3.75	V
		V_{CCO} = 3.3V, IO_Lxxy(7)	–0.3	–	3.75	V
		$V_{CCO} \leq 2.5V$, IO	–0.3	–	$V_{CCO} + 0.3$(4)	V
		$V_{CCO} \leq 2.5V$, IO_Lxxy(7)	–0.3	–	$V_{CCO} + 0.3$(4)	V
	Voltage applied to all Dedicated pins relative to GND(5)		–0.3	–	$V_{CCAUX} + 0.3$(5)	V

Notes:

1. The V_{CCO} range given here spans the lowest and highest operating voltages of all supported I/O standards. The recommended V_{CCO} range specific to each of the single-ended I/O standards is given in Table 35, and that specific to the differential standards is given in Table 37.
2. Only during DCM operation is it recommended that the rate of change of V_{CCAUX} not exceed 10 mV/ms.
3. Input voltages outside the recommended range are permissible provided that the I_{IK} input diode clamp diode rating is met. Refer to Table 28.
4. Each of the User I/O and Dual-Purpose pins is associated with one of the V_{CCO} rails. Meeting the V_{IN} limit ensures that the internal diode junctions that exist between these pins and their associated V_{CCO} and GND rails do not turn on. The absolute maximum rating is provided in Table 28.
5. All Dedicated pins (PROG_B, DONE, TCK, TDI, TDO, and TMS) draw power from the V_{CCAUX} rail (2.5V). Meeting the V_{IN} max limit ensures that the internal diode junctions that exist between each of these pins and the V_{CCAUX} and GND rails do not turn on.
6. See XAPP459, *Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins on Spartan-3 Generation FPGAs*.
7. For single-ended signals that are placed on a differential-capable I/O, V_{IN} of –0.2V to –0.3V is supported but can cause increased leakage between the two pins. See the *Parasitic Leakage* section in UG331, *Spartan-3 Generation FPGA User Guide*.

Table 35: **Recommended Operating Conditions for User I/Os Using Single-Ended Standards**

Signal Standard (IOSTANDARD)	V_{CCO}			V_{REF}			V_{IL}	V_{IH}
	Min (V)	Nom (V)	Max (V)	Min (V)	Nom (V)	Max (V)	Max (V)	Min (V)
GTL[(3)]	–	–	–	0.74	0.8	0.86	V_{REF} – 0.05	V_{REF} + 0.05
GTL_DCI	–	1.2	–	0.74	0.8	0.86	V_{REF} – 0.05	V_{REF} + 0.05
GTLP[(3)]	–	–	–	0.88	1	1.12	V_{REF} – 0.1	V_{REF} + 0.1
GTLP_DCI	–	1.5	–	0.88	1	1.12	V_{REF} – 0.1	V_{REF} + 0.1
HSLVDCI_15	1.4	1.5	1.6	–	0.75	–	V_{REF} – 0.1	V_{REF} + 0.1
HSLVDCI_18	1.7	1.8	1.9	–	0.9	–	V_{REF} – 0.1	V_{REF} + 0.1
HSLVDCI_25	2.3	2.5	2.7	–	1.25	–	V_{REF} – 0.1	V_{REF} + 0.1
HSLVDCI_33	3.0	3.3	3.465	–	1.65	–	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_I, HSTL_I_DCI	1.4	1.5	1.6	0.68	0.75	0.9	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_III, HSTL_III_DCI	1.4	1.5	1.6	–	0.9	–	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_I_18, HSTL_I_DCI_18	1.7	1.8	1.9	0.8	0.9	1.1	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_II_18, HSTL_II_DCI_18	1.7	1.8	1.9	–	0.9	–	V_{REF} – 0.1	V_{REF} + 0.1
HSTL_III_18, HSTL_III_DCI_18	1.7	1.8	1.9	–	1.1	–	V_{REF} – 0.1	V_{REF} + 0.1
LVCMOS12	1.14	1.2	1.3	–	–	–	$0.37V_{CCO}$	$0.58V_{CCO}$
LVCMOS15, LVDCI_15, LVDCI_DV2_15	1.4	1.5	1.6	–	–	–	$0.30V_{CCO}$	$0.70V_{CCO}$
LVCMOS18, LVDCI_18, LVDCI_DV2_18	1.7	1.8	1.9	–	–	–	$0.30V_{CCO}$	$0.70V_{CCO}$
LVCMOS25[(4,5)], LVDCI_25, LVDCI_DV2_25[(4)]	2.3	2.5	2.7	–	–	–	0.7	1.7
LVCMOS33, LVDCI_33, LVDCI_DV2_33[(4)]	3.0	3.3	3.465	–	–	–	0.8	2.0
LVTTL	3.0	3.3	3.465	–	–	–	0.8	2.0
PCI33_3[(7)]	3.0	3.3	3.465	–	–	–	$0.30V_{CCO}$	$0.50V_{CCO}$
SSTL18_I, SSTL18_I_DCI	1.7	1.8	1.9	0.833	0.900	0.969	V_{REF} – 0.125	V_{REF} + 0.125
SSTL18_II	1.7	1.8	1.9	0.833	0.900	0.969	V_{REF} – 0.125	V_{REF} + 0.125
SSTL2_I, SSTL2_I_DCI	2.3	2.5	2.7	1.15	1.25	1.35	V_{REF} – 0.15	V_{REF} + 0.15
SSTL2_II, SSTL2_II_DCI	2.3	2.5	2.7	1.15	1.25	1.35	V_{REF} – 0.15	V_{REF} + 0.15

Notes:

1. Descriptions of the symbols used in this table are as follows:
   V_{CCO} – the supply voltage for output drivers as well as LVCMOS, LVTTL, and PCI inputs
   V_{REF} – the reference voltage for setting the input switching threshold
   V_{IL} – the input voltage that indicates a Low logic level
   V_{IH} – the input voltage that indicates a High logic level
2. For device operation, the maximum signal voltage (V_{IH} max) may be as high as V_{IN} max. See Table 28.
3. Because the GTL and GTLP standards employ open-drain output buffers, V_{CCO} lines do not supply current to the I/O circuit, rather this current is provided using an external pull-up resistor connected from the I/O pin to a termination voltage (V_{TT}). Nevertheless, the voltage applied to the associated V_{CCO} lines must always be at or above V_{TT} and I/O pad voltages.
4. There is approximately 100 mV of hysteresis on inputs using LVCMOS25 or LVCMOS33 standards.
5. All dedicated pins (M0-M2, CCLK, PROG_B, DONE, HSWAP_EN, TCK, TDI, TDO, and TMS) use the LVCMOS standard and draw power from the V_{CCAUX} rail (2.5V). The dual-purpose configuration pins (DIN/D0, D1-D7, CS_B, RDWR_B, BUSY/DOUT, and INIT_B) use the LVCMOS standard before the user mode. For these pins, apply 2.5V to the V_{CCO} Bank 4 and V_{CCO} Bank 5 rails at power-on and throughout configuration. For information concerning the use of 3.3V signals, see 3.3V-Tolerant Configuration Interface, page 47.
6. The Global Clock Inputs (GCLK0-GCLK7) are dual-purpose pins to which any signal standard can be assigned.
7. For more information, see XAPP457.

Switching Characteristics

All Spartan-3 devices are available in two speed grades: –4 and the higher performance –5. Switching characteristics in this document may be designated as Advance, Preliminary, or Production. Each category is defined as follows:

Advance: These specifications are based on simulations only and are typically available soon after establishing FPGA specifications. Although speed grades with this designation are considered relatively stable and conservative, some under-reported delays may still occur.

Preliminary: These specifications are based on complete early silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting preliminary delays is greatly reduced compared to Advance data.

Production: These specifications are approved once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Production-quality systems must use FPGA designs compiled using a Production status speed file. FPGAs designs using a less mature speed file designation may only be used during system prototyping or preproduction qualification. FPGA designs using Advance or Preliminary status speed files should never be used in a production-quality system.

Whenever a speed file designation changes, as a device matures toward Production status, rerun the Xilinx ISE software on the FPGA design to ensure that the FPGA design incorporates the latest timing information and software updates.

Xilinx ISE Software Updates: http://www.xilinx.com/support/download/index.htm

All specified limits are representative of worst-case supply voltage and junction temperature conditions. Unless otherwise noted, the following applies: Parameter values apply to all Spartan-3 devices. All parameters representing voltages are measured with respect to GND.

Selected timing parameters and their representative values are included below either because they are important as general design requirements or they indicate fundamental device performance characteristics. The Spartan-3 FPGA v1.38 speed files are the original source for many but not all of the values. The v1.38 speed files are available in Xilinx Integrated Software Environment (ISE) software version 8.2i.

The speed grade designations for these files are shown in Table 39. For more complete, more precise, and worst-case data, use the values reported by the Xilinx static timing analyzer (TRACE in the Xilinx development software) and back-annotated to the simulation netlist.

Table 39: **Spartan-3 FPGA Speed Grade Designations (ISE v8.2i or Later)**

<table>
<tr><th>Device</th><th>Advance</th><th>Preliminary</th><th>Production</th></tr>
<tr><td>XC3S50</td><td></td><td></td><td rowspan="7">-4, -5 (v1.37 and later)</td></tr>
<tr><td>XC3S200</td><td></td><td></td></tr>
<tr><td>XC3S400</td><td></td><td></td></tr>
<tr><td>XC3S1000</td><td></td><td></td></tr>
<tr><td>XC3S1500</td><td></td><td></td></tr>
<tr><td>XC3S2000</td><td></td><td></td></tr>
<tr><td>XC3S4000</td><td></td><td></td></tr>
<tr><td>XC3S5000</td><td></td><td></td><td>-4, -5 (v1.38 and later)</td></tr>
</table>

Table 41: **System-Synchronous Pin-to-Pin Setup and Hold Times for the IOB Input Path**

Symbol	Description	Conditions	Device	Speed Grade -5 Min	Speed Grade -4 Min	Units
Setup Times						
T_{PSDCM}	When writing to the Input Flip-Flop (IFF), the time from the setup of data at the Input pin to the active transition at a Global Clock pin. The DCM is in use. No Input Delay is programmed.	LVCMOS25[(2)], IOBDELAY = NONE, with DCM[(4)]	XC3S50	2.37	2.71	ns
			XC3S200	2.13	2.35	ns
			XC3S400	2.15	2.36	ns
			XC3S1000	2.58	2.95	ns
			XC3S1500	2.55	2.91	ns
			XC3S2000	2.59	2.96	ns
			XC3S4000	2.76	3.15	ns
			XC3S5000	2.69	3.08	ns
T_{PSFD}	When writing to IFF, the time from the setup of data at the Input pin to an active transition at the Global Clock pin. The DCM is not in use. The Input Delay is programmed.	LVCMOS25[(2)], IOBDELAY = IFD, without DCM	XC3S50	3.00	3.46	ns
			XC3S200	2.63	3.02	ns
			XC3S400	2.50	2.87	ns
			XC3S1000	3.50	4.03	ns
			XC3S1500	3.78	4.35	ns
			XC3S2000	4.98	5.73	ns
			XC3S4000	5.25	6.05	ns
			XC3S5000	5.37	6.18	ns
Hold Times						
T_{PHDCM}	When writing to IFF, the time from the active transition at the Global Clock pin to the point when data must be held at the Input pin. The DCM is in use. No Input Delay is programmed.	LVCMOS25[(3)], IOBDELAY = NONE, with DCM[(4)]	XC3S50	–0.45	–0.40	ns
			XC3S200	–0.12	–0.05	ns
			XC3S400	–0.12	–0.05	ns
			XC3S1000	–0.43	–0.38	ns
			XC3S1500	–0.45	–0.40	ns
			XC3S2000	–0.47	–0.42	ns
			XC3S4000	–0.61	–0.56	ns
			XC3S5000	–0.62	–0.57	ns

Phase Shifter (PS)

Phase shifter operation is only supported if the DLL is in low-frequency mode, see Table 58. Fixed phase shift requires ISE software version 10.1.03 (or later).

Table 62: **Recommended Operating Conditions for the PS in Variable Phase Mode**

Symbol	Description	Frequency Mode/ F_{CLKIN} Range		Speed Grade -5 Min	Speed Grade -5 Max	Speed Grade -4 Min	Speed Grade -4 Max	Units
Operating Frequency Ranges								
PSCLK_FREQ (F_{PSCLK})	Frequency for the PSCLK input	Low		1	167	1	167	MHz
Input Pulse Requirements								
PSCLK_PULSE	PSCLK pulse width as a percentage of the PSCLK period	Low	$F_{CLKIN} \leq$ 100 MHz	40%	60%	40%	60%	-
			F_{CLKIN} > 100 MHz	45%	55%	45%	55%	-

Table 63: **Switching Characteristics for the PS in Variable or Fixed Phase Shift Mode**

Symbol	Description	Frequency Mode/ F_{CLKIN} Range	Speed Grade -5 Min	Speed Grade -5 Max	Speed Grade -4 Min	Speed Grade -4 Max	Units
Phase Shifting Range							
FINE_SHIFT_RANGE	Phase shift range	Low	–	10.0	–	10.0	ns
Lock Time							
LOCK_DLL_PS	When using the PS in conjunction with the DLL: The time from deassertion at the DCM's Reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase.	18 MHz $\leq F_{CLKIN} \leq$ 30 MHz	–	3.28	–	3.28	ms
		30 MHz < $F_{CLKIN} \leq$ 40 MHz	–	2.56	–	2.56	ms
		40 MHz < $F_{CLKIN} \leq$ 50 MHz	–	1.60	–	1.60	ms
		50 MHz < $F_{CLKIN} \leq$ 60 MHz	–	1.00	–	1.00	ms
		60 MHz < $F_{CLKIN} \leq$ 165 MHz	–	0.88	–	0.88	ms
LOCK_DLL_PS_FX	When using the PS in conjunction with the DLL and DFS: The time from deassertion at the DCM's Reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase.	Low	–	10.40	–	10.40	ms

Notes:
1. The numbers in this table are based on the operating conditions set forth in Table 32 and Table 62.
2. The PS specifications in this table apply when the PS attribute CLKOUT_PHASE_SHIFT= VARIABLE or FIXED.

Table 70: **Spartan-3 FPGA Pin Definitions *(Cont'd)***

Pin Name	Direction	Description
TDI	Input	**JTAG Test Data Input:** TDI is the serial data input for all JTAG instruction and data registers. This pin has an internal pull-up resistor to VCCAUX during configuration.
TMS	Input	**JTAG Test Mode Select:** The serial TMS input controls the operation of the JTAG port. This pin has an internal pull-up resistor to VCCAUX during configuration.
TDO	Output	**JTAG Test Data Output:** TDO is the serial data output for all JTAG instruction and data registers. This pin has an internal pull-up resistor to VCCAUX during configuration.
VCCO: I/O bank output voltage supply pins		
VCCO_#	Supply	**Power Supply for Output Buffer Drivers (per bank):** These pins power the output drivers within a specific I/O bank.
VCCAUX: Auxiliary voltage supply pins		
VCCAUX	Supply	**Power Supply for Auxiliary Circuits:** +2.5V power pins for auxiliary circuits, including the Digital Clock Managers (DCMs), the dedicated configuration pins (CONFIG), and the dedicated JTAG pins. All VCCAUX pins must be connected.
VCCINT: Internal core voltage supply pins		
VCCINT	Supply	**Power Supply for Internal Core Logic:** +1.2V power pins for the internal logic. All pins must be connected.
GND: Ground supply pins		
GND	Supply	**Ground:** Ground pins, which are connected to the power supply's return path. All pins must be connected.
N.C.: Unconnected package pins		
N.C.		**Unconnected Package Pin:** These package pins are unconnected.

Notes:

1. All unused inputs and bidirectional pins must be tied either High or Low. For unused enable inputs, apply the level that disables the associated function. One common approach is to activate internal pull-up or pull-down resistors. An alternative approach is to externally connect the pin to either VCCO or GND.
2. All outputs are of the totem-pole type — i.e., they can drive High as well as Low logic levels — except for the cases where "Open Drain" is indicated. The latter can only drive a Low logic level and require a pull-up resistor to produce a High logic level.

Detailed, Functional Pin Descriptions

I/O Type: Unrestricted, General-purpose I/O Pins

After configuration, I/O-type pins are inputs, outputs, bidirectional I/O, three-state outputs, open-drain outputs, or open-source outputs, as defined in the application

Pins labeled "IO" support all SelectIO™ interface signal standards except differential standards. A given device at most only has a few of these pins.

A majority of the general-purpose I/O pins are labeled in the format "IO_Lxxy_#". These pins support all SelectIO signal standards, including the differential standards such as LVDS, ULVDS, BLVDS, RSDS, or LDT.

For additional information, see IOBs, page 10

Package Thermal Characteristics

The power dissipated by an FPGA application has implications on package selection and system design. The power consumed by a Spartan-3 FPGA is reported using either the XPower Estimator (XPE) or the XPower Analyzer integrated in the Xilinx ISE development software. Table 86 provides the thermal characteristics for the various Spartan-3 device/package offerings.

The junction-to-case thermal resistance (θ_{JC}) indicates the difference between the temperature measured on the package body (case) and the die junction temperature per watt of power consumption. The junction-to-board (θ_{JB}) value similarly reports the difference between the board and junction temperature. The junction-to-ambient (θ_{JA}) value reports the temperature difference per watt between the ambient environment and the junction temperature. The θ_{JA} value is reported at different air velocities, measured in linear feet per minute (LFM). The "Still Air (0 LFM)" column shows the θ_{JA} value in a system without a fan. The thermal resistance drops with increasing air flow.

Table 86: **Spartan-3 FPGA Package Thermal Characteristics**

Package	Device	Junction-to-Case (θ_{JC})	Junction-to-Board (θ_{JB})	Junction-to-Ambient (θ_{JA}) at Different Air Flows				Units
				Still Air (0 LFM)	250 LFM	500 LFM	750 LFM	
VQ(G)100	XC3S50	12.0	–	46.2	38.4	35.8	34.9	°C/Watt
	XC3S200	10.0	–	40.5	33.7	31.3	30.5	°C/Watt
CP(G)132[(1)]	XC3S50	14.5	32.8	53.0	46.4	44.0	42.5	°C/Watt
TQ(G)144	XC3S50	7.6	–	41.0	31.9	27.2	25.6	°C/Watt
	XC3S200	6.6	–	34.5	26.9	23.0	21.6	°C/Watt
	XC3S400	6.1	–	32.8	25.5	21.8	20.4	°C/Watt
PQ(G)208	XC3S50	10.6	–	37.4	27.6	24.4	22.6	°C/Watt
	XC3S200	8.6	–	36.2	26.7	23.6	21.9	°C/Watt
	XC3S400	7.5	–	35.4	26.1	23.1	21.4	°C/Watt
FT(G)256	XC3S200	9.9	22.9	31.7	25.6	24.5	24.2	°C/Watt
	XC3S400	7.9	19.0	28.4	22.8	21.5	21.0	°C/Watt
	XC3S1000	5.6	14.7	24.8	19.2	18.0	17.5	°C/Watt
FG(G)320	XC3S400	8.9	13.9	24.4	19.0	17.8	17.0	°C/Watt
	XC3S1000	7.8	11.8	22.3	17.0	15.8	15.0	°C/Watt
	XC3S1500	6.7	9.8	20.3	15.18	13.8	13.1	°C/Watt
FG(G)456	XC3S400	8.4	13.6	20.8	15.1	13.9	13.4	°C/Watt
	XC3S1000	6.4	10.6	19.3	13.4	12.3	11.7	°C/Watt
	XC3S1500	4.9	8.3	18.3	12.4	11.2	10.7	°C/Watt
	XC3S2000	3.7	6.5	17.7	11.7	10.5	10.0	°C/Watt
FG(G)676	XC3S1000	6.0	10.4	17.9	13.7	12.6	12.0	°C/Watt
	XC3S1500	4.9	8.8	16.8	12.4	11.3	10.7	°C/Watt
	XC3S2000	4.1	7.9	15.6	11.1	9.9	9.3	°C/Watt
	XC3S4000	3.6	7.0	15.0	10.5	9.3	8.7	°C/Watt
	XC3S5000	3.4	6.3	14.7	10.3	9.1	8.5	°C/Watt
FG(G)900	XC3S2000	3.7	7.0	14.3	10.3	9.3	8.8	°C/Watt
	XC3S4000	3.3	6.4	13.6	9.7	8.7	8.2	°C/Watt
	XC3S5000	2.9	5.9	13.1	9.2	8.1	7.6	°C/Watt

FG320: 320-lead Fine-pitch Ball Grid Array

The 320-lead fine-pitch ball grid array package, FG320, supports three different Spartan-3 devices, including the XC3S400, the XC3S1000, and the XC3S1500. The footprint for all three devices is identical, as shown in Table 98 and Figure 50.

The FG320 package is an 18 x 18 array of solder balls minus the four center balls.

All the package pins appear in Table 98 and are sorted by bank number, then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at http://www.xilinx.com/support/documentation/data_ sheets/s3_pin.zip.

Pinout Table

Table 98: **FG320 Package Pinout**

Bank	XC3S400, XC3S1000, XC3S1500 Pin Name	FG320 Pin Number	Type
0	IO	D9	I/O
0	IO	E7	I/O
0	IO/VREF_0	B3	VREF
0	IO/VREF_0	D6	VREF
0	IO_L01N_0/VRP_0	A2	DCI
0	IO_L01P_0/VRN_0	A3	DCI
0	IO_L09N_0	B4	I/O
0	IO_L09P_0	C4	I/O
0	IO_L10N_0	C5	I/O
0	IO_L10P_0	D5	I/O
0	IO_L15N_0	A4	I/O
0	IO_L15P_0	A5	I/O
0	IO_L25N_0	B5	I/O
0	IO_L25P_0	B6	I/O
0	IO_L27N_0	C7	I/O
0	IO_L27P_0	D7	I/O
0	IO_L28N_0	C8	I/O
0	IO_L28P_0	D8	I/O
0	IO_L29N_0	E8	I/O
0	IO_L29P_0	F8	I/O
0	IO_L30N_0	A7	I/O
0	IO_L30P_0	A8	I/O
0	IO_L31N_0	B9	I/O
0	IO_L31P_0/VREF_0	A9	VREF
0	IO_L32N_0/GCLK7	E9	GCLK
0	IO_L32P_0/GCLK6	F9	GCLK
0	VCCO_0	B8	VCCO
0	VCCO_0	C6	VCCO
0	VCCO_0	G8	VCCO

Table 98: **FG320 Package Pinout *(Cont'd)***

Bank	XC3S400, XC3S1000, XC3S1500 Pin Name	FG320 Pin Number	Type
3	IO_L24N_3	M18	I/O
3	IO_L24P_3	N17	I/O
3	IO_L27N_3	L14	I/O
3	IO_L27P_3	L13	I/O
3	IO_L34N_3	L15	I/O
3	IO_L34P_3/VREF_3	L16	VREF
3	IO_L35N_3	L18	I/O
3	IO_L35P_3	L17	I/O
3	IO_L39N_3	K13	I/O
3	IO_L39P_3	K14	I/O
3	IO_L40N_3/VREF_3	K17	VREF
3	IO_L40P_3	K18	I/O
3	VCCO_3	K12	VCCO
3	VCCO_3	L12	VCCO
3	VCCO_3	N16	VCCO
4	IO	P12	I/O
4	IO	V14	I/O
4	IO/VREF_4	R10	VREF
4	IO/VREF_4	U13	VREF
4	IO/VREF_4	V17	VREF
4	IO_L01N_4/VRP_4	U16	DCI
4	IO_L01P_4/VRN_4	V16	DCI
4	IO_L06N_4/VREF_4	P14	VREF
4	IO_L06P_4	R14	I/O
4	IO_L09N_4	U15	I/O
4	IO_L09P_4	V15	I/O
4	IO_L10N_4	T14	I/O
4	IO_L10P_4	U14	I/O
4	IO_L25N_4	R13	I/O
4	IO_L25P_4	P13	I/O
4	IO_L27N_4/DIN/D0	T12	DUAL
4	IO_L27P_4/D1	R12	DUAL
4	IO_L28N_4	V12	I/O
4	IO_L28P_4	V11	I/O
4	IO_L29N_4	R11	I/O
4	IO_L29P_4	T11	I/O
4	IO_L30N_4/D2	N11	DUAL
4	IO_L30P_4/D3	P11	DUAL
4	IO_L31N_4/INIT_B	U10	DUAL

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
1	N.C. (◆)	IO_L18P_1	IO_L18P_1	IO_L18P_1	IO(3)	C18	I/O
1	IO_L19N_1	IO_L19N_1	IO_L19N_1	IO_L19N_1	IO_L19N_1	F17	I/O
1	IO_L19P_1	IO_L19P_1	IO_L19P_1	IO_L19P_1	IO_L19P_1	G17	I/O
1	IO_L22N_1	IO_L22N_1	IO_L22N_1	IO_L22N_1	IO_L22N_1	D17	I/O
1	IO_L22P_1	IO_L22P_1	IO_L22P_1	IO_L22P_1	IO_L22P_1	E17	I/O
1	N.C. (◆)	IO_L23N_1	IO_L23N_1	IO_L23N_1	IO_L23N_1	A17	I/O
1	N.C. (◆)	IO_L23P_1	IO_L23P_1	IO_L23P_1	IO_L23P_1	B17	I/O
1	IO_L24N_1	IO_L24N_1	IO_L24N_1	IO_L24N_1	IO_L24N_1	G16	I/O
1	IO_L24P_1	IO_L24P_1	IO_L24P_1	IO_L24P_1	IO_L24P_1	H16	I/O
1	IO_L25N_1	IO_L25N_1	IO_L25N_1	IO_L25N_1	IO_L25N_1	E16	I/O
1	IO_L25P_1	IO_L25P_1	IO_L25P_1	IO_L25P_1	IO_L25P_1	F16	I/O
1	N.C. (◆)	IO_L26N_1	IO_L26N_1	IO_L26N_1	IO_L26N_1	A16	I/O
1	N.C. (◆)	IO_L26P_1	IO_L26P_1	IO_L26P_1	IO_L26P_1	B16	I/O
1	IO_L27N_1	IO_L27N_1	IO_L27N_1	IO_L27N_1	IO_L27N_1	G15	I/O
1	IO_L27P_1	IO_L27P_1	IO_L27P_1	IO_L27P_1	IO_L27P_1	H15	I/O
1	IO_L28N_1	IO_L28N_1	IO_L28N_1	IO_L28N_1	IO_L28N_1	E15	I/O
1	IO_L28P_1	IO_L28P_1	IO_L28P_1	IO_L28P_1	IO_L28P_1	F15	I/O
1	IO_L29N_1	IO_L29N_1	IO_L29N_1	IO_L29N_1	IO_L29N_1	A15	I/O
1	IO_L29P_1	IO_L29P_1	IO_L29P_1	IO_L29P_1	IO_L29P_1	B15	I/O
1	IO_L30N_1	IO_L30N_1	IO_L30N_1	IO_L30N_1	IO_L30N_1	G14	I/O
1	IO_L30P_1	IO_L30P_1	IO_L30P_1	IO_L30P_1	IO_L30P_1	H14	I/O
1	IO_L31N_1/VREF_1	IO_L31N_1/VREF_1	IO_L31N_1/VREF_1	IO_L31N_1/VREF_1	IO_L31N_1/VREF_1	D14	VREF
1	IO_L31P_1	IO_L31P_1	IO_L31P_1	IO_L31P_1	IO_L31P_1	E14	I/O
1	IO_L32N_1/GCLK5	IO_L32N_1/GCLK5	IO_L32N_1/GCLK5	IO_L32N_1/GCLK5	IO_L32N_1/GCLK5	B14	GCLK
1	IO_L32P_1/GCLK4	IO_L32P_1/GCLK4	IO_L32P_1/GCLK4	IO_L32P_1/GCLK4	IO_L32P_1/GCLK4	C14	GCLK
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	C16	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	C20	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	H17	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	H18	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	J14	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	J15	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	J16	VCCO
1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	VCCO_1	K14	VCCO
2	N.C. (◆)	N.C. (■)	IO	IO	IO	F22	I/O
2	IO_L01N_2/VRP_2	IO_L01N_2/VRP_2	IO_L01N_2/VRP_2	IO_L01N_2/VRP_2	IO_L01N_2/VRP_2	C25	DCI
2	IO_L01P_2/VRN_2	IO_L01P_2/VRN_2	IO_L01P_2/VRN_2	IO_L01P_2/VRN_2	IO_L01P_2/VRN_2	C26	DCI
2	IO_L02N_2	IO_L02N_2	IO_L02N_2	IO_L02N_2	IO_L02N_2	E23	I/O
2	IO_L02P_2	IO_L02P_2	IO_L02P_2	IO_L02P_2	IO_L02P_2	E24	I/O
2	IO_L03N_2/VREF_2	IO_L03N_2/VREF_2(1)	IO_L03N_2/VREF_2	IO_L03N_2/VREF_2	IO_L03N_2/VREF_2	D25	VREF(1)
2	IO_L03P_2	IO_L03P_2	IO_L03P_2	IO_L03P_2	IO_L03P_2	D26	I/O
2	N.C. (◆)	IO_L05N_2	IO_L05N_2	IO_L05N_2	IO_L05N_2	E25	I/O
2	N.C. (◆)	IO_L05P_2	IO_L05P_2	IO_L05P_2	IO_L05P_2	E26	I/O

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
N/A	GND	GND	GND	GND	GND	R16	GND
N/A	GND	GND	GND	GND	GND	R17	GND
N/A	GND	GND	GND	GND	GND	R23	GND
N/A	GND	GND	GND	GND	GND	T10	GND
N/A	GND	GND	GND	GND	GND	T11	GND
N/A	GND	GND	GND	GND	GND	T12	GND
N/A	GND	GND	GND	GND	GND	T13	GND
N/A	GND	GND	GND	GND	GND	T14	GND
N/A	GND	GND	GND	GND	GND	T15	GND
N/A	GND	GND	GND	GND	GND	T16	GND
N/A	GND	GND	GND	GND	GND	T17	GND
N/A	GND	GND	GND	GND	GND	U11	GND
N/A	GND	GND	GND	GND	GND	U12	GND
N/A	GND	GND	GND	GND	GND	U15	GND
N/A	GND	GND	GND	GND	GND	U16	GND
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A2	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A9	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A18	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	A25	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AE1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AE26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF2	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF9	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF18	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	AF25	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	B1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	B26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	J1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	J26	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	V1	VCCAUX
N/A	VCCAUX	VCCAUX	VCCAUX	VCCAUX	VCCAUX	V26	VCCAUX
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	H8	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	H19	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J10	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	J18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K10	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	K18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U10	VCCINT

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
4	IO_L31P_4/DOUT/BUSY	IO_L31P_4/DOUT/BUSY	AH16	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	AJ16	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	AK16	GCLK
4	N.C. (◆)	IO_L33N_4	AH25	I/O
4	N.C. (◆)	IO_L33P_4	AJ25	I/O
4	N.C. (◆)	IO_L34N_4	AE25	I/O
4	N.C. (◆)	IO_L34P_4	AE24	I/O
4	N.C. (◆)	IO_L35N_4	AG24	I/O
4	N.C. (◆)	IO_L35P_4	AH24	I/O
4	N.C. (◆)	IO_L38N_4	AJ24	I/O
4	N.C. (◆)	IO_L38P_4	AK24	I/O
4	VCCO_4	VCCO_4	Y17	VCCO
4	VCCO_4	VCCO_4	Y18	VCCO
4	VCCO_4	VCCO_4	AD18	VCCO
4	VCCO_4	VCCO_4	AH18	VCCO
4	VCCO_4	VCCO_4	Y19	VCCO
4	VCCO_4	VCCO_4	AB20	VCCO
4	VCCO_4	VCCO_4	AD22	VCCO
4	VCCO_4	VCCO_4	AH22	VCCO
4	VCCO_4	VCCO_4	AF24	VCCO
4	VCCO_4	VCCO_4	AH26	VCCO
5	IO	IO	AE6	I/O
5	IO	IO	AB10	I/O
5	IO	IO	AA11	I/O
5	IO	IO	AA15	I/O
5	IO	IO	AE15	I/O
5	IO/VREF_5	IO/VREF_5	AH4	VREF
5	IO/VREF_5	IO/VREF_5	AK15	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	AK4	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	AJ4	DUAL
5	IO_L02N_5	IO_L02N_5	AK5	I/O
5	IO_L02P_5	IO_L02P_5	AJ5	I/O
5	IO_L03N_5	IO_L03N_5	AF6	I/O
5	IO_L03P_5	IO_L03P_5	AG5	I/O
5	IO_L04N_5	IO_L04N_5	AJ6	I/O
5	IO_L04P_5	IO_L04P_5	AH6	I/O
5	IO_L05N_5	IO_L05N_5	AE7	I/O
5	IO_L05P_5	IO_L05P_5	AD7	I/O
5	IO_L06N_5	IO_L06N_5	AH7	I/O
5	IO_L06P_5	IO_L06P_5	AG7	I/O

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
1	VCCO_1	VCCO_1	M22	VCCO
2	IO	IO	G33	I/O
2	IO	IO	G34	I/O
2	IO	IO	U25	I/O
2	IO	IO	U26	I/O
2	IO_L01N_2/VRP_2	IO_L01N_2/VRP_2	C33	DCI
2	IO_L01P_2/VRN_2	IO_L01P_2/VRN_2	C34	DCI
2	IO_L02N_2	IO_L02N_2	D33	I/O
2	IO_L02P_2	IO_L02P_2	D34	I/O
2	IO_L03N_2/VREF_2	IO_L03N_2/VREF_2	E32	VREF
2	IO_L03P_2	IO_L03P_2	E33	I/O
2	IO_L04N_2	IO_L04N_2	F31	I/O
2	IO_L04P_2	IO_L04P_2	F32	I/O
2	IO_L05N_2	IO_L05N_2	G29	I/O
2	IO_L05P_2	IO_L05P_2	G30	I/O
2	IO_L06N_2	IO_L06N_2	H29	I/O
2	IO_L06P_2	IO_L06P_2	H30	I/O
2	IO_L07N_2	IO_L07N_2	H33	I/O
2	IO_L07P_2	IO_L07P_2	H34	I/O
2	IO_L08N_2	IO_L08N_2	J28	I/O
2	IO_L08P_2	IO_L08P_2	J29	I/O
2	IO_L09N_2/VREF_2	IO_L09N_2/VREF_2	H31	VREF
2	IO_L09P_2	IO_L09P_2	J31	I/O
2	IO_L10N_2	IO_L10N_2	J32	I/O
2	IO_L10P_2	IO_L10P_2	J33	I/O
2	IO_L11N_2	IO_L11N_2	J27	I/O
2	IO_L11P_2	IO_L11P_2	K26	I/O
2	IO_L12N_2	IO_L12N_2	K27	I/O
2	IO_L12P_2	IO_L12P_2	K28	I/O
2	IO_L13N_2	IO_L13N_2	K29	I/O
2	IO_L13P_2/VREF_2	IO_L13P_2/VREF_2	K30	VREF
2	IO_L14N_2	IO_L14N_2	K31	I/O
2	IO_L14P_2	IO_L14P_2	K32	I/O
2	IO_L15N_2	IO_L15N_2	K33	I/O
2	IO_L15P_2	IO_L15P_2	K34	I/O
2	IO_L16N_2	IO_L16N_2	L25	I/O
2	IO_L16P_2	IO_L16P_2	L26	I/O
2	N.C. (◆)	IO_L17N_2	L28	I/O
2	N.C. (◆)	IO_L17P_2/ VREF_2	L29	VREF

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
N/A	VCCINT	VCCINT	Y22	VCCINT
VCCAUX	CCLK	CCLK	AL31	CONFIG
VCCAUX	DONE	DONE	AD24	CONFIG
VCCAUX	HSWAP_EN	HSWAP_EN	L11	CONFIG
VCCAUX	M0	M0	AL4	CONFIG
VCCAUX	M1	M1	AK4	CONFIG
VCCAUX	M2	M2	AG8	CONFIG
VCCAUX	PROG_B	PROG_B	D4	CONFIG
VCCAUX	TCK	TCK	D31	JTAG
VCCAUX	TDI	TDI	E4	JTAG
VCCAUX	TDO	TDO	E31	JTAG
VCCAUX	TMS	TMS	H27	JTAG